Unit in mm

TOSHIBA DIODE SILICON EPITAXIAL PLANAR TYPE

H N 2 D 0 2 F U

ULTRA HIGH SPEED SWITCHING APPLICATION.

HN2D02FU is composed of 3 independent diodes.

Low Forward Voltage $: V_{F(3)} = 0.98V (Typ.)$

Fast Reverse Recovery Time : $t_{rr} = 1.6ns$ (Typ.)

Small Total Capacitance $: C_T = 0.5pF (Typ.)$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Maximum (Peak) Reverse Voltage	$v_{ m RM}$	85	V
Reverse Voltage	$ m v_R$	80	V
Maximum (Peak) Forward Current	${ m I_{FM}}$	240*	mA
Average Forward Current	I_{O}	80*	mA
Surge Current (10ms)	$I_{ ext{FSM}}$	1*	A
Power Dissipation	P	200	mW
Junction Temperature	$T_{\rm j}$	125	°C
Storage Temperature	$ m T_{stg}$	-55~125	°C

* : This is the Maximum Ratings of single diode (Q1 or Q2 or Q3). In the case of using 2 or 3 diodes, the Maximum Ratings per diode is 75% of the single diode one.

2.1 ± 0.1 1.25 ± 0.1 1. ANODE ANODE ANODE CATHODE 5. CATHODE CATHODE US6 **JEDEC**

1-2T1E

Weight: 6.8mg

TOSHIBA

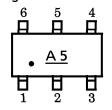
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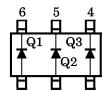
ELECTRICAL CHARACTERISTICS (Q1, Q2, Q3 COMMON, Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	$V_{F(1)}$	$I_{\mathbf{F}} = 1 \text{mA}$	_	0.62	_	
	$V_{F(2)}$	$I_{\mathbf{F}} = 10 \text{mA}$	_	0.75	_	v
	$V_{F(3)}$	$I_{ m F}\!=\!100{ m mA}$	_	0.98	1.20	
Reverse Currunt	$I_{R(1)}$	$V_R = 30V$	_	_	0.1	$\mu \mathbf{A}$
	I _{R (2)}	$V_R = 80V$	_	_	0.5	
Total Capacitance	C_{T}	$V_R=0$, f=1MHz	_	0.5	3.0	pF
Reverse Recovery Time	$t_{ m rr}$	I _F =10mA (Fig. 1)	_	1.6	4.0	ns

Marking

PIN ASSIGNMENT (TOP VIEW)

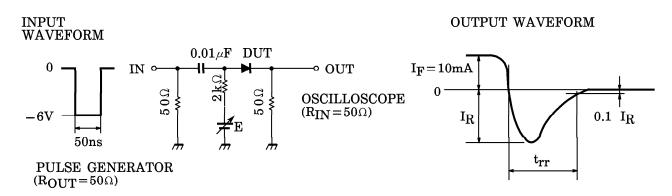


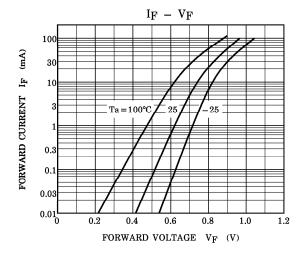


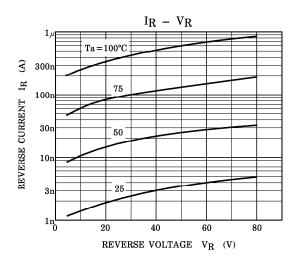
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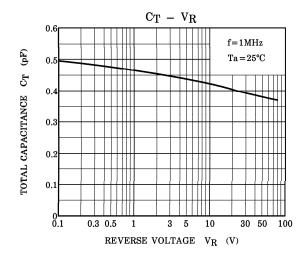
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Fig. 1 : REVERSE RECOVERY TIME (t_{rr}) TEST CIRCUIT









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